



Differential Reflective Metrology An innovative variability measurement for advanced FD-SOI material

Jean-Michel Billiez (Soitec, France)





- 1 FD-SOI, technology to meet market requirements
- 2 One innovative metrology for Å control in HVM
- 3 Layer thickness variation modeling
- 4 Innovative FD-SOI thickness control at all scales







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FD-SOI, Processor & Connectivity SOC



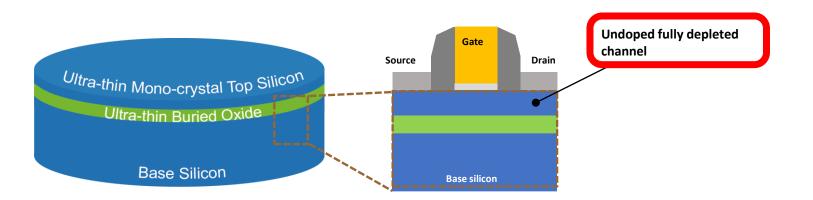
• IDM & IC design early adopters

✓ Microcontrollers and processors / nodes 65nm, 28nm, 22nm, 12nm

• Customer requirements

- ✓ Power-efficient (Mobile),
- ✓ Highly reliable and high voltage integration (Automotive)
- ✓ Easy analog/RF integration (5G)
- ✓ Cost & battery efficiency (IoT)
- ✓ Performance computing (Edge AI)

Planar FD-SOI transistor



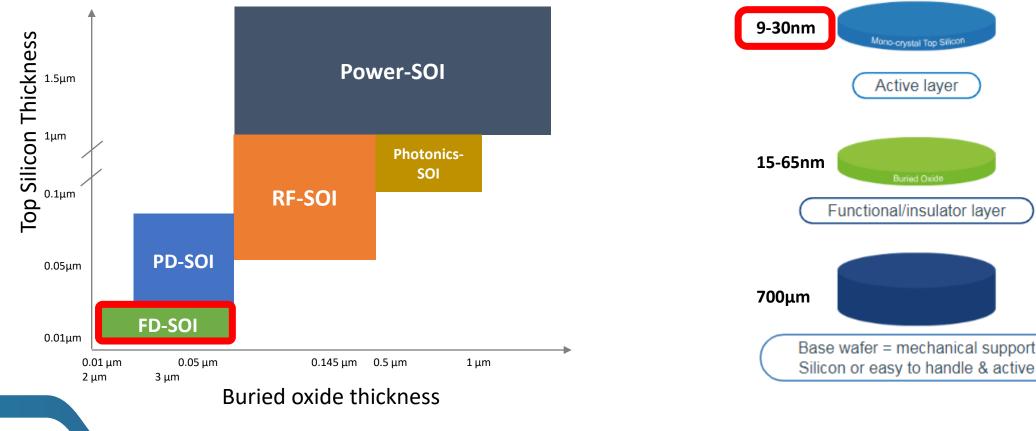






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• Thinnest Silicon On Insulator (SOI) portfolio product



Indicative layer thickness

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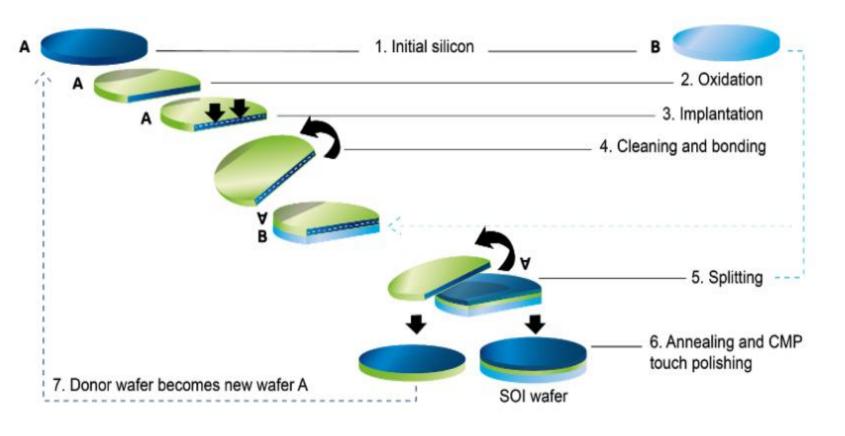
Revolutionary Smart Cut[™]



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• A mature technology for FD-SOI

- ✓ Industrial manufacturability
- \checkmark Flexibility of material integration







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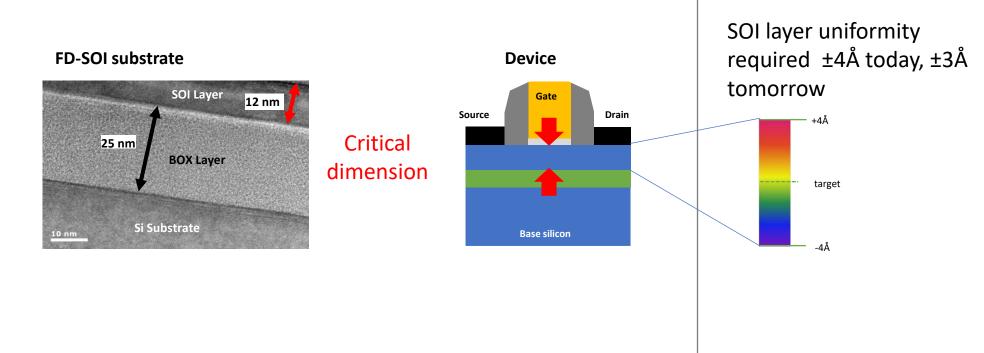


FD-SOI, key parameter



• Control of SOI thickness is a key parameter

- ✓ Contributes to device performance
- ✓ Extremely uniform SOI and BOX layers are required



8Å over full wafer

= 5mm over Europe bounder Portugal-Poland



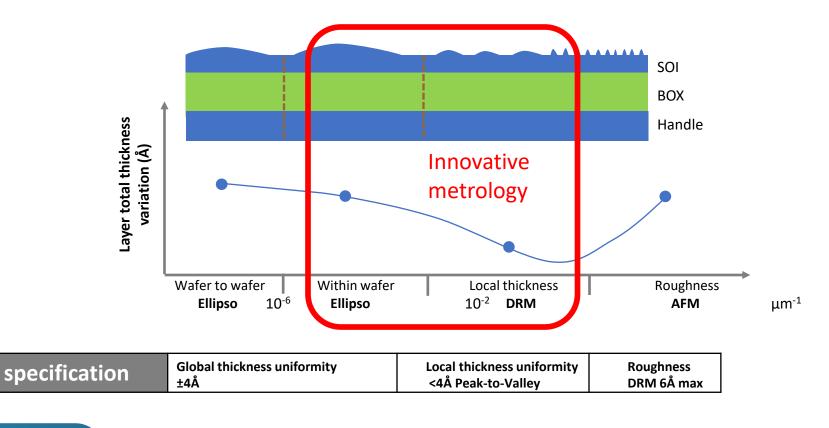






• An innovative metrology for all included SOI thickness control

✓ All frequencies which contribute to SOI thickness variation





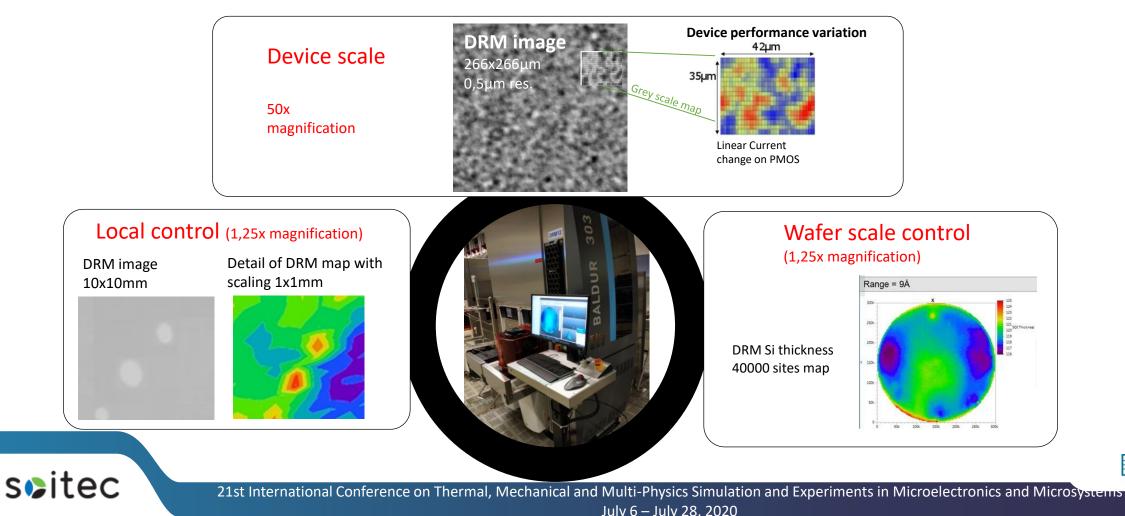




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• Differential Reflective Microscopy (DRM)

✓ IP 2013 > 1st Gen tool 2016 (Roughness) > 2nd Gen tool optimized for local scale & wafer scale (2019)





• Based on the dependence of the optical reflectivity of a layer on its thickness

✓ Reflectivity calculations using matrix formalism

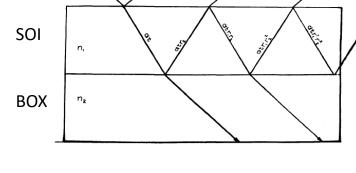
✓ Matlab realization to model reflectivity in 2 layer material substrate (thanks to E. Navarro)

Fresnel complex reflection and transmission coefficients

Reflectivity for SOI stack = function (thickness_{soi}, thickness_{BOX}, polarization, angle, wavelength)

In optical microscope: random polarization, angle integrated over Numerical Aperture, wavelength selected by interferentiel filter (±5nm)





Source: P.-E. Acosta-Alba et al., ECS Journal of Solid State Science and Technology, 2013

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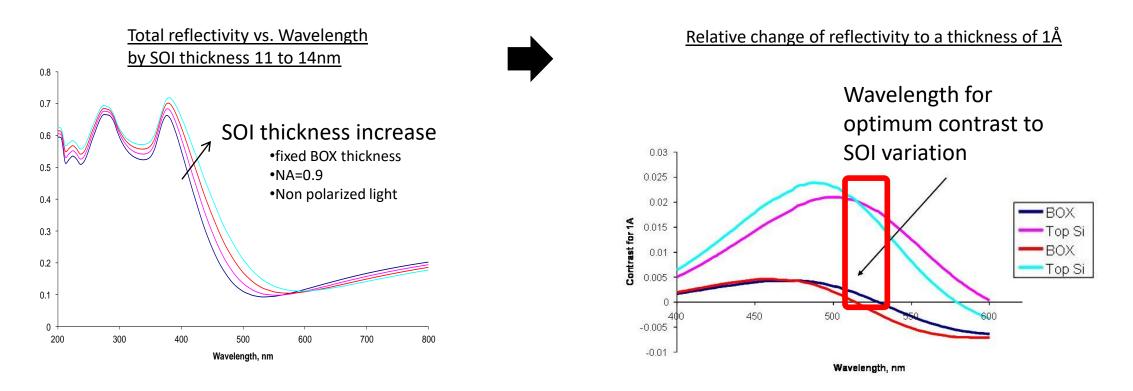


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• Total reflectivity depends on thickness change of 2 layers

✓ Reflectivity becomes only sensitive to SOI layer thickness variation at specific wavelength







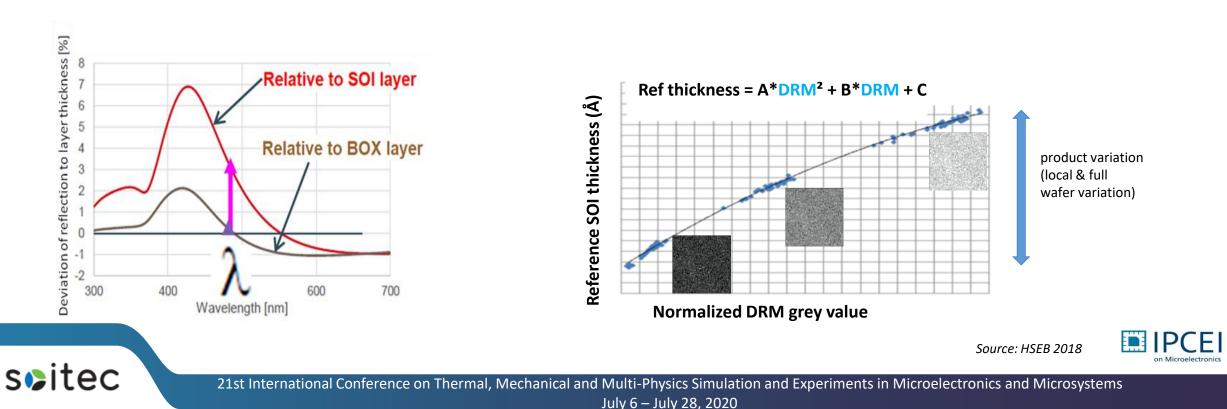
Thickness variation modeling



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- 1st Gen DRM: 1 wavelength system (2016)
 - ✓ Calibration of total reflectivity against thickness
 - \checkmark >100 sites covering the full range of product variation
 - ✓ Ellipsometry is reference metrology for very thin wafers (spot size 50µm)

• DRM value is transformed into thickness by 2nd order polynome (statistical approach)



Thickness variation modeling

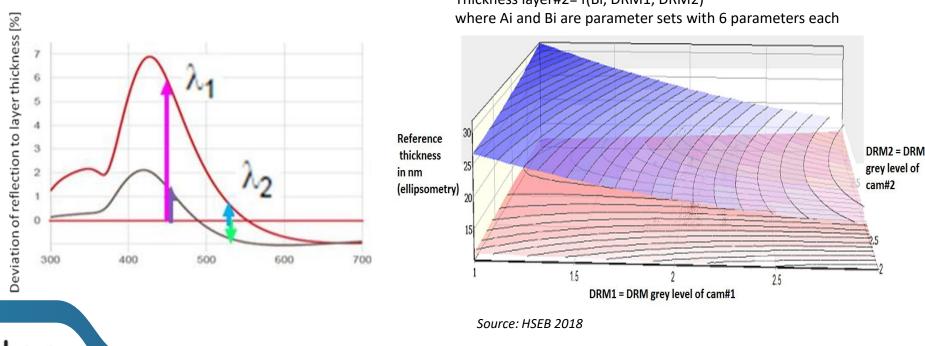


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• 2nd Gen DRM: 2 wavelenth system (2019)

- \checkmark 2 detectors and perfect alignment of images
- \checkmark >100 sites covering the full range of product variation of both layers
- ✓ DRM transformed into thickness by approximation in 2nd order polynome



Thickness layer#1 = f(Ai, DRM1, DRM2) Thickness layer#2= f(Bi, DRM1, DRM2) where Ai and Bi are parameter sets with 6 parameters each

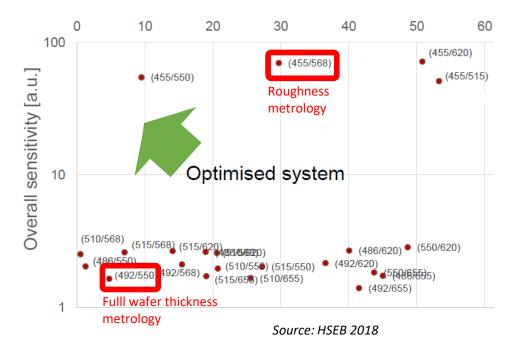




• Selection of appropriate pair of filters

✓ maximize sensitivity to SOI thickness variation and minimize residual contribution of BOX

✓ 6 pre-determined filters for optimum products flexibility



Sensitivity vs. degree of cross-correlation between SOI and BOX layers





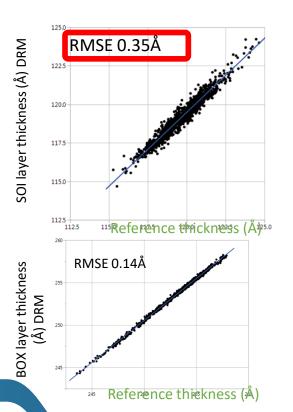
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Accuracy of DRM technology

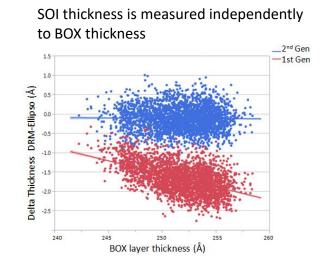


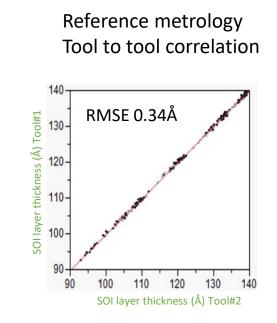
Accuracy equivalent to ellipsometer

✓ Site to site correlation: DRM 266*266µm (smallest size) vs. Ellipsometer 50µm beam size



DRM











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Device scale metrology



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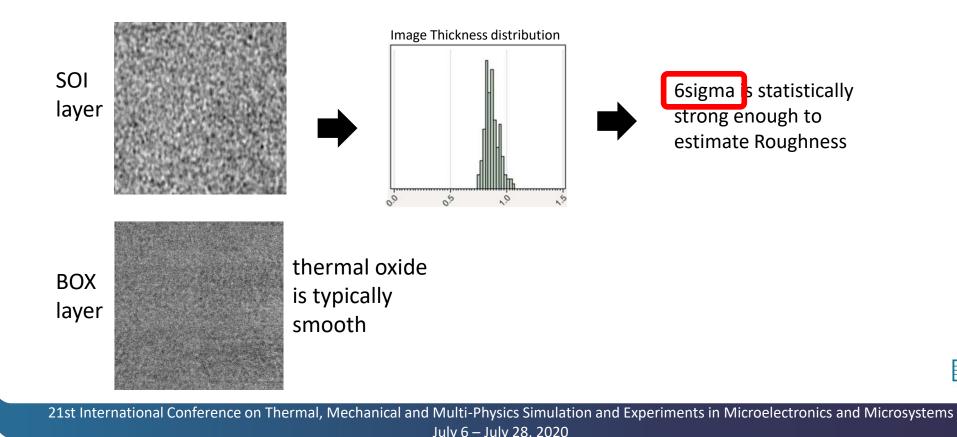
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Roughness modelization

- ✓ thickness image 266µmx266µm
- ✓ 1 Million pixels

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✓ 0.5µm optical resolution

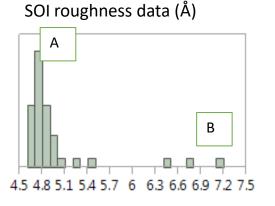


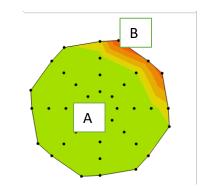
Device scale thickness variability



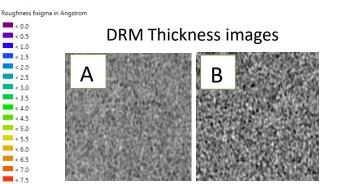
• High performance metrology

✓ Accuracy of metrology enables to exhibits small differences

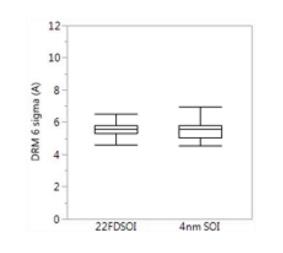




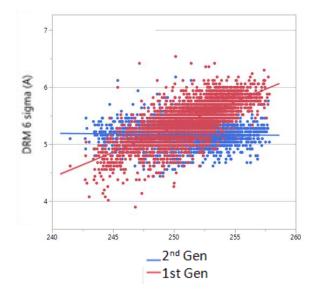
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6sigma performance vs technology



6sigma dependency to BOX thickness



BOX layer thickness (Å)



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21st International Conference on Thermal, Mechanical and Multi-Physics Simulation and Experiments in Microelectronics and Microsystems

July 6 – July 28. 2020

Full wafer scale metrology

ELECTRONICS PACKAGING SOCIETY

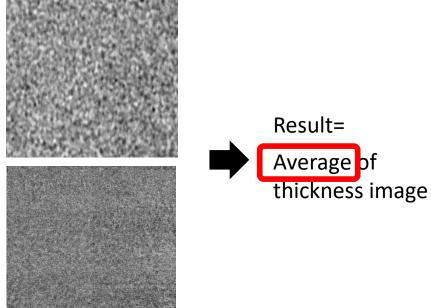
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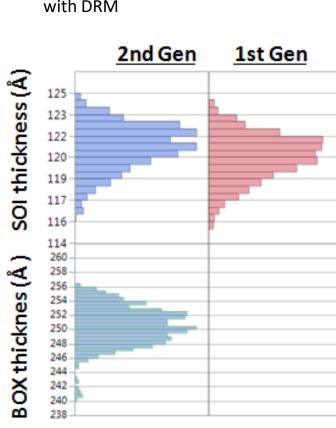
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• Thickness modelization

✓ thickness image 10mmx10mm✓ 12µm optical resolution

Thickness image of SOI layer

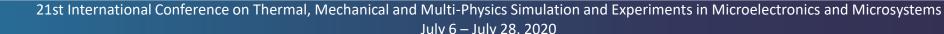




SOI and BOX layers thickness variation with DRM

Thickness image of BOX layer

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Full wafer thickness variability



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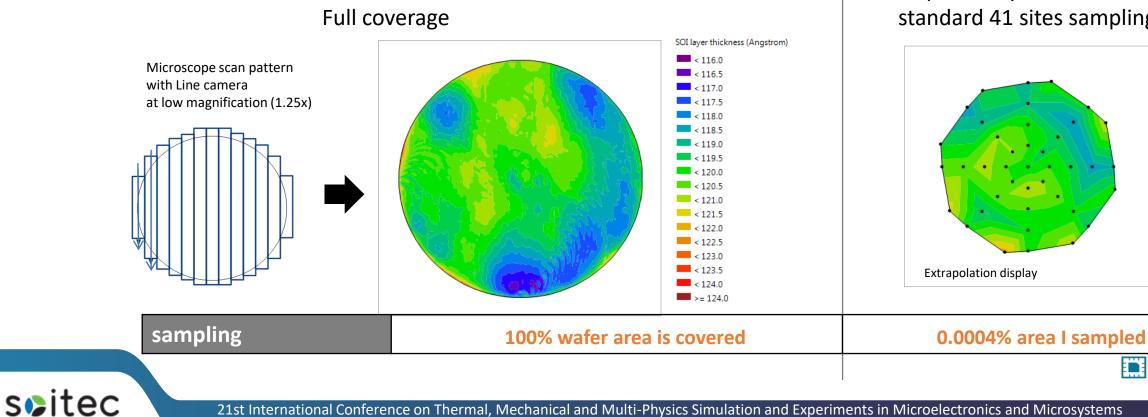
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• Full wafer scan for extremely high sampling

✓ DRM 100% wafer coverage at high throughput

DRM

 \checkmark Whereas Ellipsometer spot size is 40µm and 41 standard site map



July 6 – July 28. 2020

Ellipsometry standard 41 sites sampling

Sizable scan of thickness variability

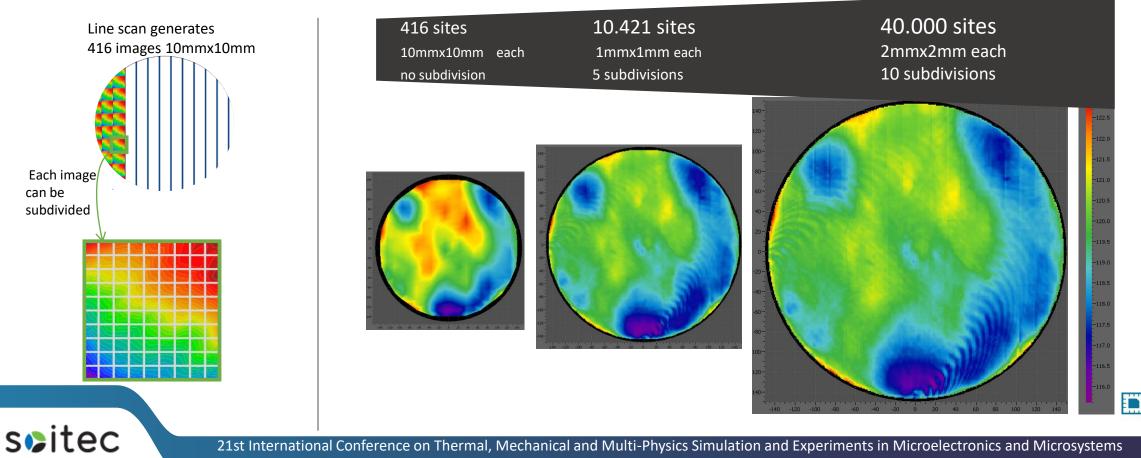


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• Metrology can adapt to device dimension

- ✓ 1 thickness value by image or subdivision
- \checkmark 1 additional thickness value by subdivision of image



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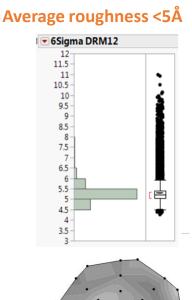
Conclusion



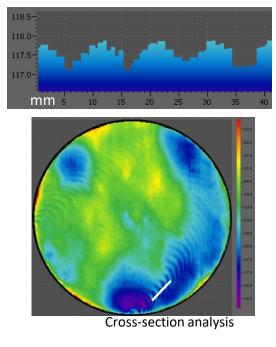
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• DRM is innovative metrology for extensive control of FD-SOI thickness uniformity

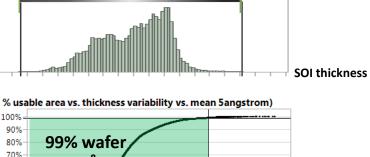
- ✓ Thickness variability within device scale
- \checkmark Local thickness control at device scale
- ✓ 100% wafer control

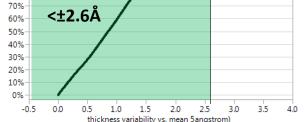


FD-SOI Local thickness profile <1Å variation



99,97% wafer within ±4Å









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Differential Reflective Metrology: An innovative variability measurement for advanced FD-SOI material (support of TF1 Energy Efficient Chips in IPCEI)

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